

RF Power Field Effect Transistor

N-Channel Enhancement-Mode Lateral MOSFET

Designed for PCN and PCS base station applications with frequencies from 1800 to 2000 MHz. Suitable for FM, TDMA, CDMA and multicarrier amplifier applications. To be used in Class AB for PCN-PCS/cellular radio and WLL applications.

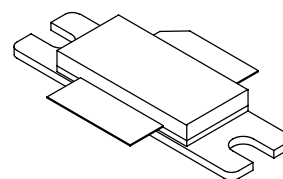
- Typical GSM Performance @ 1805 MHz
Power Gain — 13 dB @ 60 Watts
Efficiency — 45% @ 60 Watts
- Capable of Handling 10:1 VSWR, @ 26 Vdc, 1840 MHz, 60 Watts CW Output Power

Features

- Internally Matched for Ease of Use
- High Gain, High Efficiency and High Linearity
- Integrated ESD Protection
- Designed for Maximum Gain and Insertion Phase Flatness
- Excellent Thermal Stability
- Available with Low Gold Plating Thickness on Leads. L Suffix Indicates 40 μ " Nominal.
- RoHS Compliant
- In Tape and Reel. R3 Suffix = 250 Units per 56 mm, 13 inch Reel.

MRF18060ALR3

**1805-1880 MHz, 60 W, 26 V
LATERAL N-CHANNEL
RF POWER MOSFET**



**CASE 465-06, STYLE 1
NI-780**

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Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	-0.5, +65	Vdc
Gate-Source Voltage	V _{GS}	-0.5, +15	Vdc
Total Device Dissipation @ T _C ≥ 25°C Derate above 25°C	P _D	180 1.03	W W/°C
Storage Temperature Range	T _{stg}	- 65 to +150	°C
Case Operating Temperature	T _C	150	°C
Operating Junction Temperature	T _J	200	°C

Table 2. Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case	R _{θJC}	0.97	°C/W

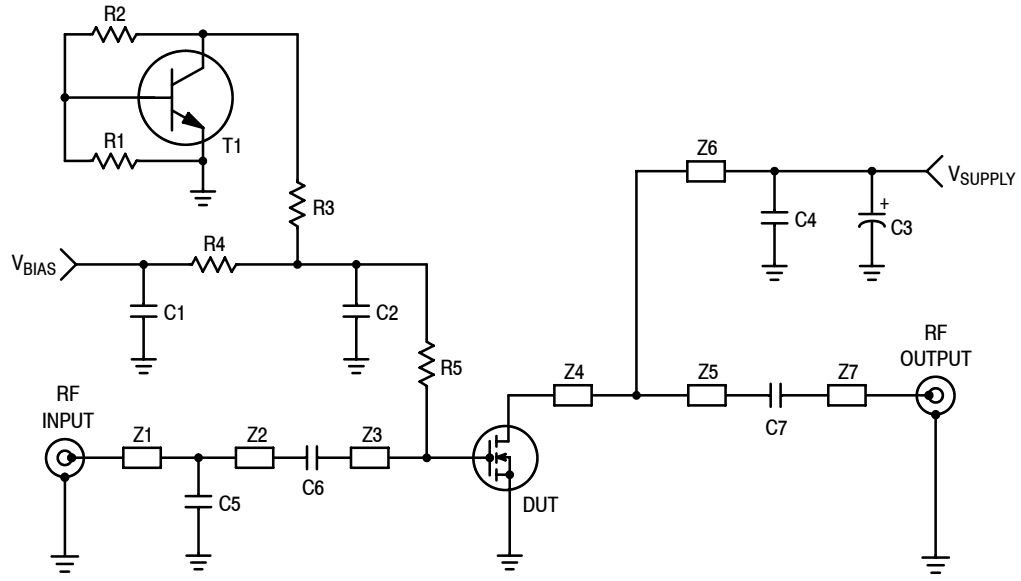
Table 3. ESD Protection Characteristics

Test Conditions	Class
Human Body Model	2 (Minimum)
Machine Model	M3 (Minimum)

Table 4. Electrical Characteristics ($T_C = 25^\circ\text{C}$ unless otherwise noted)

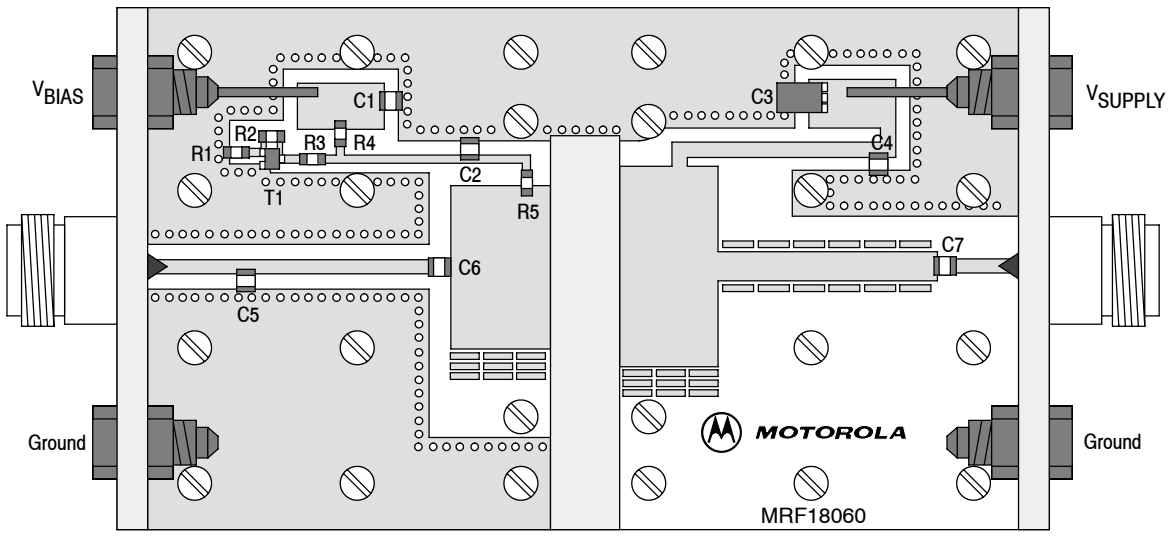
Characteristic	Symbol	Min	Typ	Max	Unit
Off Characteristics					
Drain-Source Breakdown Voltage ($V_{GS} = 0\text{ Vdc}$, $I_D = 10\ \mu\text{Adc}$)	$V_{(BR)DSS}$	65	—	—	Vdc
Zero Gate Voltage Drain Current ($V_{DS} = 26\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$)	I_{DSS}	—	—	6	μAdc
Gate-Source Leakage Current ($V_{GS} = 5\text{ Vdc}$, $V_{DS} = 0\text{ Vdc}$)	I_{GSS}	—	—	1	μAdc
On Characteristics					
Gate Threshold Voltage ($V_{DS} = 10\text{ Vdc}$, $I_D = 300\ \mu\text{Adc}$)	$V_{GS(th)}$	2	—	4	Vdc
Gate Quiescent Voltage ($V_{DS} = 26\text{ Vdc}$, $I_D = 500\text{ mAdc}$)	$V_{GS(Q)}$	2.5	3.9	4.5	Vdc
Drain-Source On-Voltage ($V_{GS} = 10\text{ Vdc}$, $I_D = 2\text{ Adc}$)	$V_{DS(on)}$	—	0.27	—	Vdc
Dynamic Characteristics					
Input Capacitance (Including Input Matching Capacitor in Package) (1) ($V_{DS} = 26\text{ Vdc} \pm 30\text{ mV(rms)ac}$ @ 1 MHz, $V_{GS} = 0\text{ Vdc}$)	C_{iss}	—	160	—	pF
Output Capacitance (1) ($V_{DS} = 26\text{ Vdc} \pm 30\text{ mV(rms)ac}$ @ 1 MHz, $V_{GS} = 0\text{ Vdc}$)	C_{oss}	—	740	—	pF
Reverse Transfer Capacitance ($V_{DS} = 26\text{ Vdc} \pm 30\text{ mV(rms)ac}$ @ 1 MHz, $V_{GS} = 0\text{ Vdc}$)	C_{rss}	—	2.7	—	pF
Functional Tests (In Freescale Test Fixture, 50 ohm system)					
Common-Source Amplifier Power Gain @ 60 W ($V_{DD} = 26\text{ Vdc}$, $I_{DQ} = 500\text{ mA}$, $f = 1805\text{ MHz}$)	G_{ps}	11.5	13	—	dB
Drain Efficiency @ 60 W ($V_{DD} = 26\text{ Vdc}$, $I_{DQ} = 500\text{ mA}$, $f = 1805\text{ MHz}$)	η	43	45	—	%
Input Return Loss ($V_{DD} = 26\text{ Vdc}$, $P_{out} = 60\text{ W CW}$, $I_{DQ} = 500\text{ mA}$, $f = 1805\text{ MHz}$)	IRL	—	—	-10	dB

1. Part is internally matched both on input and output.



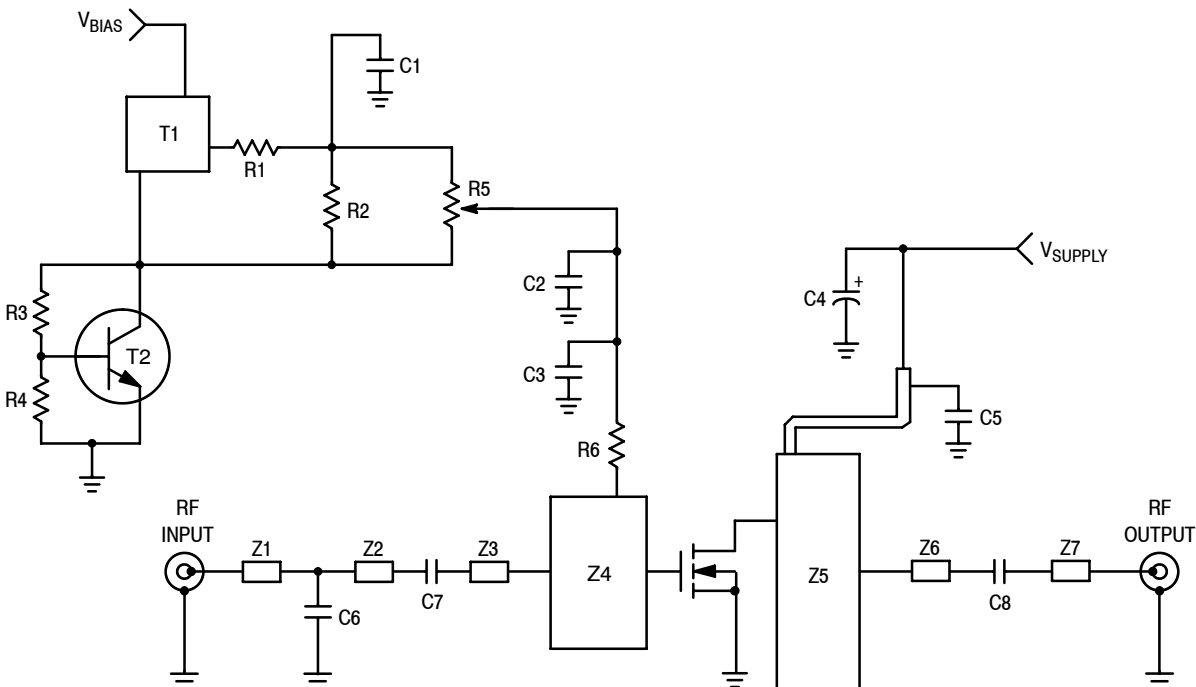
C1	100 nF Chip Capacitor (1203)	Z1	0.47" x 0.09" Microstrip
C2, C4, C7	10 pF Chip Capacitors	Z2	1.16" x 0.09" Microstrip
C3	10 μ F, 35 V Electrolytic Capacitor	Z3	0.57" x 0.95" Microstrip
C5	1.2 pF Chip Capacitor	Z4	0.59" x 1.18" Microstrip
C6	1.0 pF Chip Capacitor	Z5	1.26" x 0.15" Microstrip
R1, R3	2.2 k Ω Chip Resistors (0805)	Z6	1.15" x 0.09" Microstrip
R2, R4	2.7 k Ω Chip Resistors (0805)	Z7	0.37" x 0.09" Microstrip
R5	1.1 k Ω Chip Resistor (0805)		
T1	BC847 Transistor SOT-23		

Figure 1. 1805 - 1880 MHz Test Fixture Schematic



Freescle has begun the transition of marking Printed Circuit Boards (PCBs) with the Freescle Semiconductor signature/logo. PCBs may have either Motorola or Freescle markings during the transition period. These changes will have no impact on form, fit or function of the current product.

Figure 2. 1805 - 1880 MHz Test Fixture Component Layout

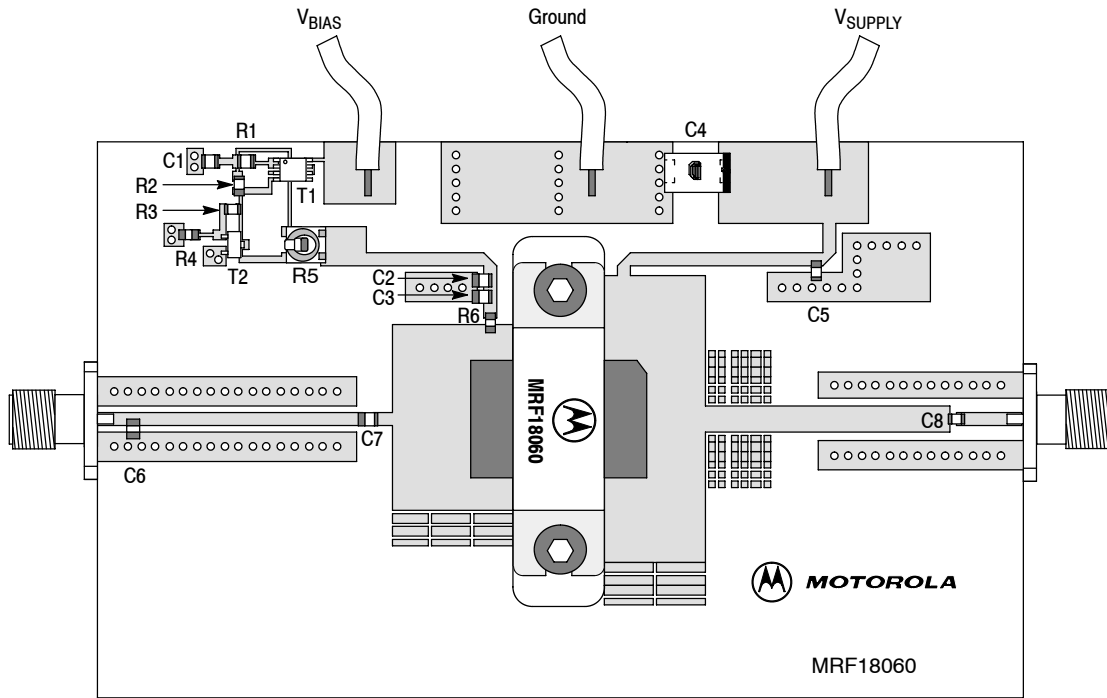


C1	1 μ F Chip Capacitor (0805)	T1	LP2951 Micro-8 Voltage Regulator
C2	100 nF Chip Capacitor (0805)	T2	BC847 SOT-23 NPN Transistor
C3, C5, C8	10 pF Chip Capacitors, ACCU-P (0805)	Z1	0.159" x 0.055" Microstrip
C4	10 μ F, 35 V Electrolytic Capacitor	Z2	0.982" x 0.055" Microstrip
C6	1.8 pF Chip Capacitor, ACCU-P (0805)	Z3	0.087" x 0.055" Microstrip
C7	1 pF Chip Capacitor, ACCU-P (0805)	Z4	0.512" x 0.787" Microstrip
R1	10 Ω Chip Resistor (0805)	Z5	0.433" x 1.220" Microstrip
R2, R6	1 k Ω Chip Resistors (0805)	Z6	1.039" x 0.118" Microstrip
R3	1.2 k Ω Chip Resistor (0805)	Z7	0.268" x 0.055" Microstrip
R4	2.2 k Ω Chip Resistor (0805)	Substrate = 0.5 mm Teflon [®] Glass, $\epsilon_r = 2.55$	
R5	5 k Ω , SMD Potentiometer		

Figure 3. 1800 - 2000 MHz Demo Board Schematic

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Freescall has begun the transition of marking Printed Circuit Boards (PCBs) with the Freescall Semiconductor signature/logo. PCBs may have either Motorola or Freescall markings during the transition period. These changes will have no impact on form, fit or function of the current product.

Figure 4. 1800 - 2000 MHz Demo Board Component Layout

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TYPICAL CHARACTERISTICS (DATA TAKEN USING WIDEBAND DEMONSTRATION BOARD)

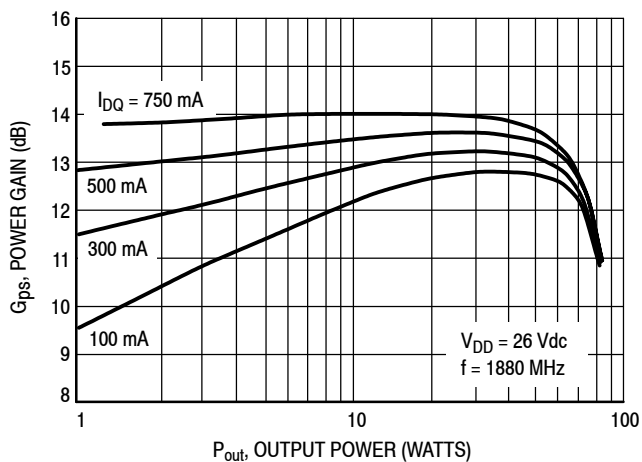


Figure 5. Power Gain versus Output Power

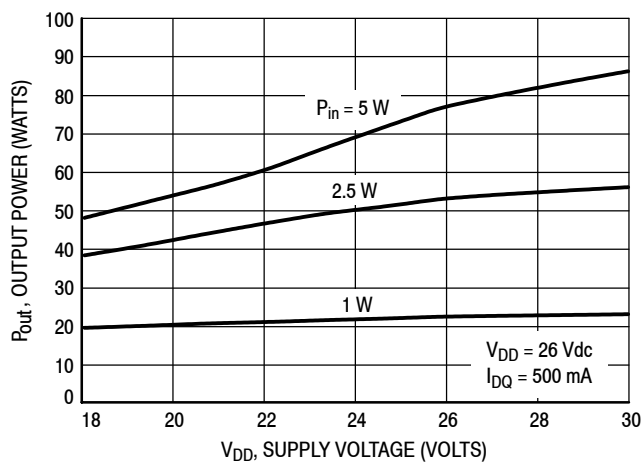


Figure 6. Output Power versus Supply Voltage

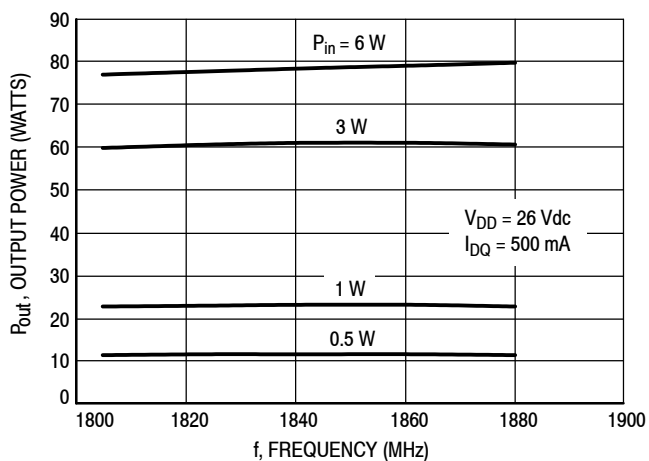


Figure 7. Output Power versus Frequency

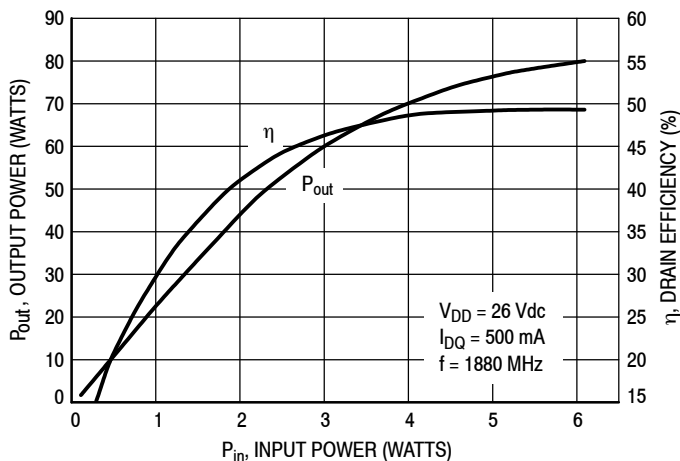


Figure 8. Output Power and Efficiency versus Input Power

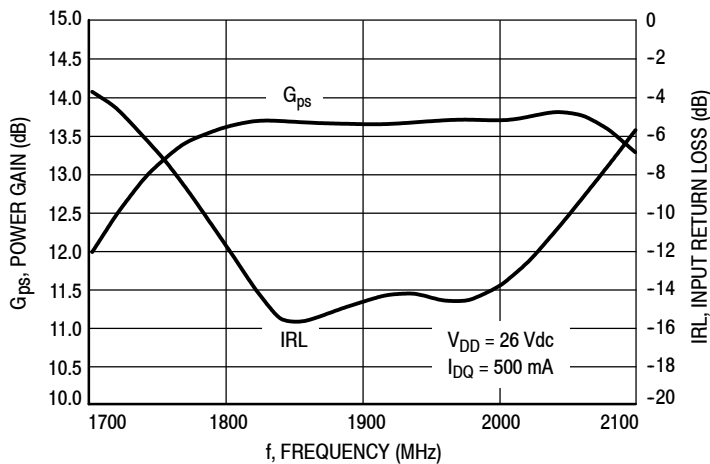
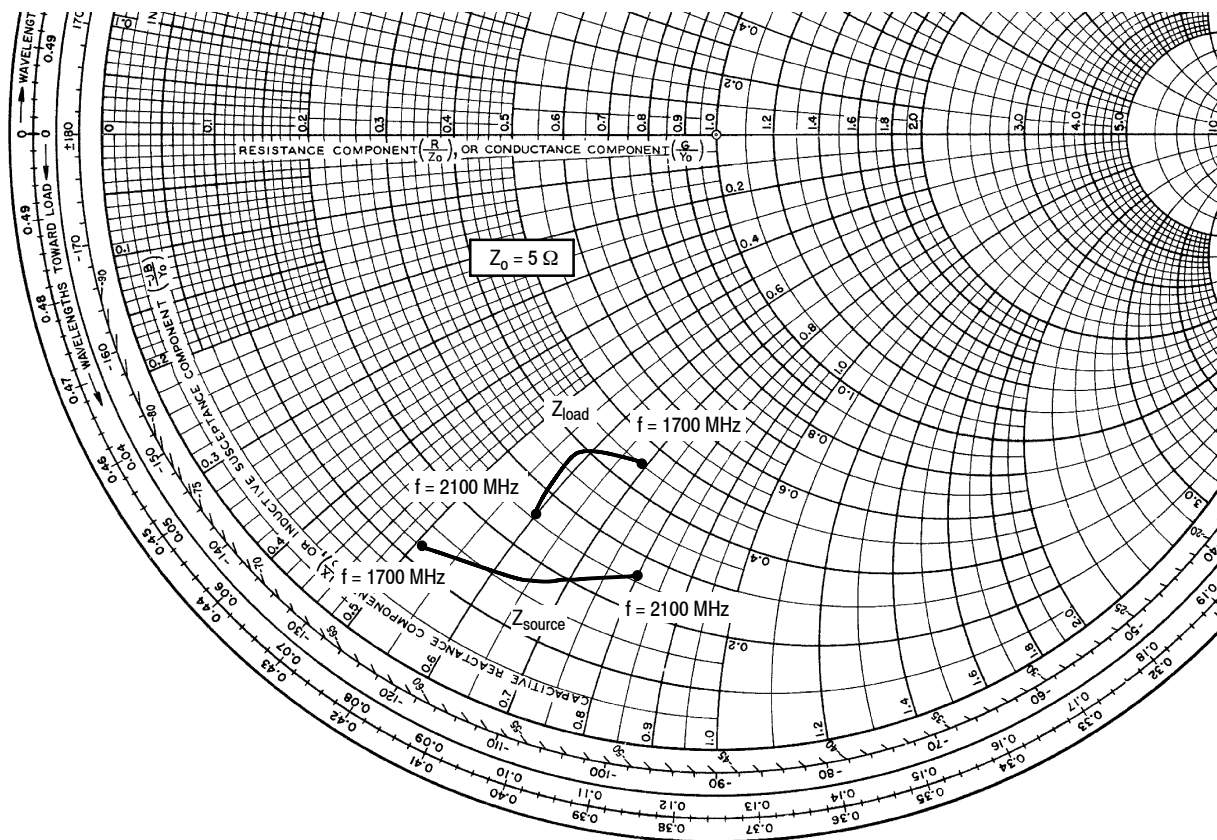


Figure 9. Wideband Gain and IRL (at Small Signal)

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$V_{DD} = 26\text{ V}$, $I_{DQ} = 500\text{ mA}$, $P_{out} = 60\text{ W CW}$

f MHz	Z_{source} Ω	Z_{load} Ω
1700	$0.60 - j2.53$	$2.27 - j3.44$
1800	$0.80 - j3.20$	$2.05 - j3.05$
1900	$0.92 - j3.42$	$1.90 - j2.90$
2000	$1.07 - j3.59$	$1.64 - j2.88$
2100	$1.31 - j4.00$	$1.29 - j2.99$

Z_{source} = Test circuit impedance as measured from gate to ground.

Z_{load} = Test circuit impedance as measured from drain to ground.

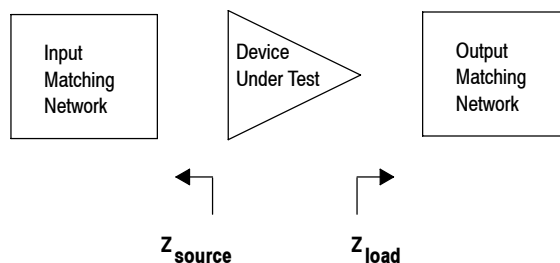
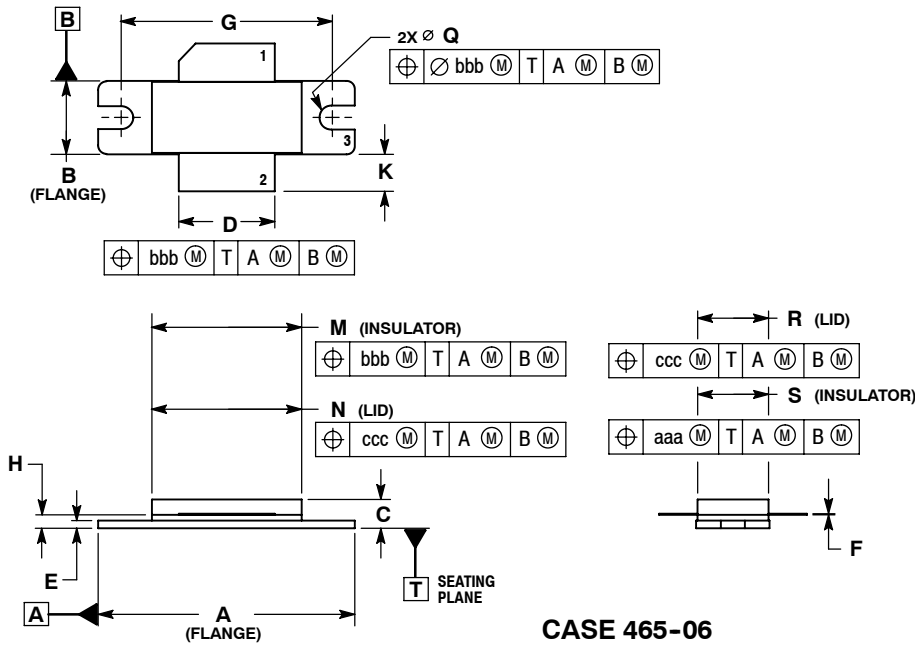


Figure 10. Series Equivalent Source and Load Impedance

PACKAGE DIMENSIONS



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1994.
 2. CONTROLLING DIMENSION: INCH.
 3. DELETED
 4. DIMENSION H IS MEASURED 0.030 (0.762) AWAY FROM PACKAGE BODY.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.335	1.345	33.91	34.16
B	0.380	0.390	9.65	9.91
C	0.125	0.170	3.18	4.32
D	0.495	0.505	12.57	12.83
E	0.035	0.045	0.89	1.14
F	0.003	0.006	0.08	0.15
G	1.100 BSC		27.94 BSC	
H	0.057	0.067	1.45	1.70
K	0.170	0.210	4.32	5.33
M	0.774	0.786	19.66	19.96
N	0.772	0.788	19.60	20.00
Q	Ø.118	Ø.138	Ø3.00	Ø3.51
R	0.365	0.375	9.27	9.53
S	0.365	0.375	9.27	9.52
aaa	0.005 REF		0.127 REF	
bbb	0.010 REF		0.254 REF	
ccc	0.015 REF		0.381 REF	

- STYLE 1:
 PIN 1. DRAIN
 2. GATE
 3. SOURCE

CASE 465-06
 ISSUE G
 NI-780
 MRF18060ALR3

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PRODUCT DOCUMENTATION

Refer to the following documents to aid your design process.

Engineering Bulletins

- EB212: Using Data Sheet Impedances for RF LDMOS Devices

REVISION HISTORY

The following table summarizes revisions to this document.

Revision	Date	Description
11	Oct. 2008	<ul style="list-style-type: none"> • Data sheet revised to reflect part status change, p. 1, including use of applicable overlay. • Modified data sheet to reflect RF Test Reduction described in Product and Process Change Notification number, PCN12779, p. 1, 2 • Added Product Documentation and Revision History, p. 9 • Data sheet split due to change in part life cycle (-1, -2 added to enable visibility on web).
	Dec. 2010	<ul style="list-style-type: none"> • MRF18060A-2 Rev. 11 (MRF18060ALR3) data sheet archived. Part no longer manufactured. See MRF18060A-1 Rev. 10 for MRF18060ALSR3.

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